



# 2019 Power Technology Roadmap

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VP Sales & Marketing Navitas  
CPSSC-PSMA Workshop 2019  
Presented with content/approval from  
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# Partnership

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- 谢谢 CPSS-PSMA Workshop

# Power Sources Manufacturers' Association

- Promotes the interests of the Power Electronics industry
- Sponsors conferences, workshops, research
- On-line industry standards database
- Power Technology Roadmap (PTR)
- PSMA is 35 years old in 2019
- *Congratulations to CPSS for 35 years in 2018!*



Capacitor



Education



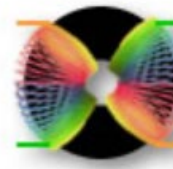
Energy Harvesting



Energy Management



Lead-Free



Magnetics



Packaging & Manufacturing



Power Technology Roadmap



Reliability



Safety & Compliance



Semiconductor



Transportation PowerElectronics

# Conferences, Workshops



中国电源学会第二十三届学术年会  
The 23<sup>rd</sup> China Power Supply Society Conference (CPSSC'2019)

2019年11月1日至4日  
地点: 深圳



2019 WiPDA

Raleigh, NC | October 29- October 31 |

7<sup>th</sup> Annual IEEE Workshop on Wide Bandgap Power Devices & Applications

The State View Hotel  
2451 Alumni Drive  
Raleigh, NC 27606



EnerHarv 2020



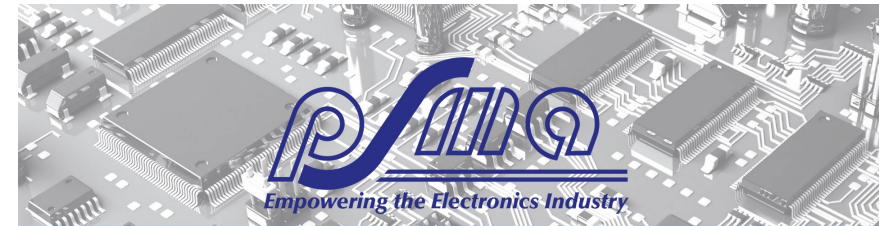
PWR  
SOC 20



3D-PEIM  
INTERNATIONAL SYMPOSIUM  
ON 3D POWER ELECTRONICS  
INTEGRATION AND MANUFACTURING

# Power Technology Roadmap (PTR)

- Guidance on
  - Product metrics
  - Technology
  - Applications
 ...for the next 3-5 years
- 17 presentations from industry on trends, new technologies
- Industry commentary on product applications and component technology
- Started 1994, now every 2 years. 2019 = 670 pages
- Based on surveys of PSMA & CPSS members - 谢谢
  - Metrics include cost, efficiency, power conversion density
  - Drivers and barriers to change are identified



## 2019 PSMA POWER TECHNOLOGY ROADMAP

### Organizing Committee Chairs

*Dhaval B. Dalal*  
ON Semiconductor

*Conor Quinn*  
Artesyn Embedded Technologies

### Segment Leaders

*Ajay Hari*  
ON Semiconductor  
*Application Trends 2015, 2017, 2019*

*Upal Sengupta*  
Continental Corporation  
*Application Trends 2019*

*Vittorio Crisafulli*  
ON Semiconductor  
*Component Technologies 2017, 2019*

*Tim McDonald*  
Infineon Technologies  
*Component Technologies 2017, 2019*

*Mark Scott*  
Miami University  
*Isolated Dc-Dc Converters 2019*

*Ian Mazza*  
Vicor Inc.  
*Isolated Dc-Dc Converters 2013, 2015, 2017, 2019*

*Xin Zhang*  
IBM  
*Non-Isolated Dc-Dc Converters 2019*

*Jeff Nilles*  
Independent Consultant  
*Non-Isolated Dc-Dc Converters 2015, 2017, 2019*

*Arnold Alderman*  
Anagenesis Inc.  
*Non-Isolated Dc-Dc Converters 2009, 2011, 2013, 2015, 2017, 2019*

*John Wiggernhorn*  
ON Semiconductor  
*Ac-Dc External Power Supplies 2013, 2015, 2017, 2019*

*Stephen Oliver*  
Navitas Semiconductor  
*Ac-Dc External Power Supplies 2017, 2019*  
*Isolated Dc-Dc Converters 2013, 2015*

*Ed Massey*  
Methode Corporation  
*Ac-Dc Front-End Power Supplies 2019*

*Robert V. White*  
Embedded Power Labs  
University Research 2019

*Brian Zahnstecher*  
PowerRox  
*Ac-Dc Front-End Power Supplies 2015, 2017, 2019*

# Roadmap: Application Trends

- Automotive / Electric Vehicle
- Battery Charging
- Data Center and Cloud Computing
- Energy Harvesting
- LED Lighting
- Variable Speed Motor Trends in HVAC and Appliance
- Renewable Energy / Grid Storage
- Safety and Compliance

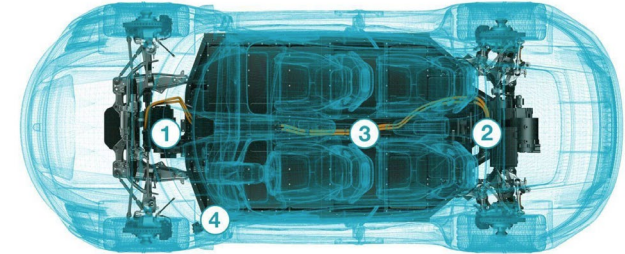


Figure 1. Porsche Taycan 800 V Powertrain (image courtesy of Porsche)  
(1) Front Motor (2) 800 V Battery (3) Rear Motor (4) Charge Inlet

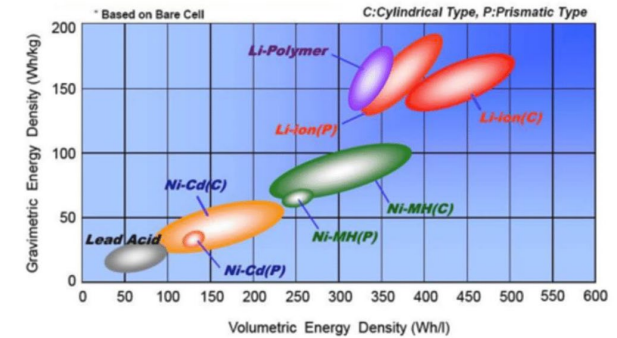
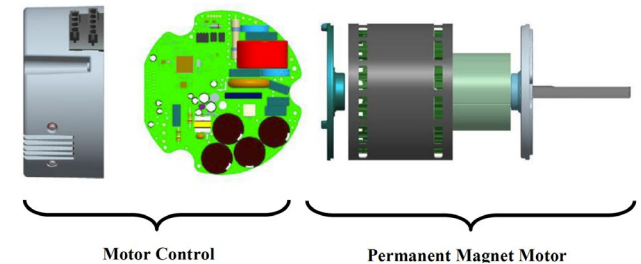


Figure 6. Comparison of Energy Density in Battery Cells  
[NASA-National Aeronautics and Space Administration]



Motor Control      Permanent Magnet Motor

Figure 32. Typical Residential HVAC Integrated Motor Drive

# Roadmap: Component Technologies

- Prismatic Aluminum Electrolytic Technology
- The Future of Magnetics
- Low Voltage MOSFETs
- Silicon Super Junction MOSFETs
- Isolated Gate Drivers
- SiC Diodes and MOSFETs Overview
- GaN Devices and Integrated Circuits
- Packaging in High Power
- First-Time-Right Discrete Power Electronic Design

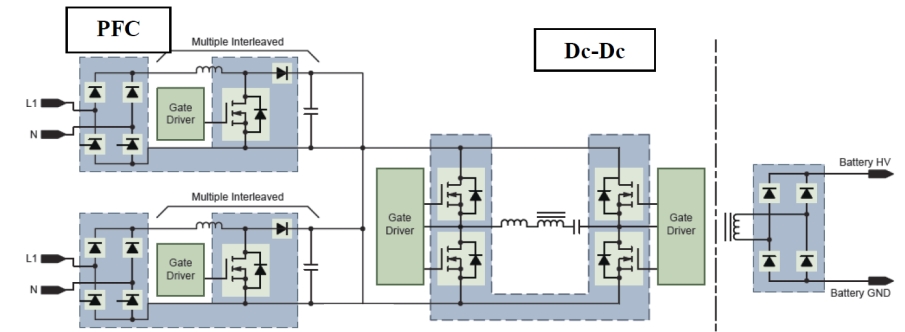


Figure 57. Circuit Scheme of an EV On-Board Charger  
(source: <http://www.onsemi.com/pub/Collateral/BRD8044-D.PDF>, 2017)

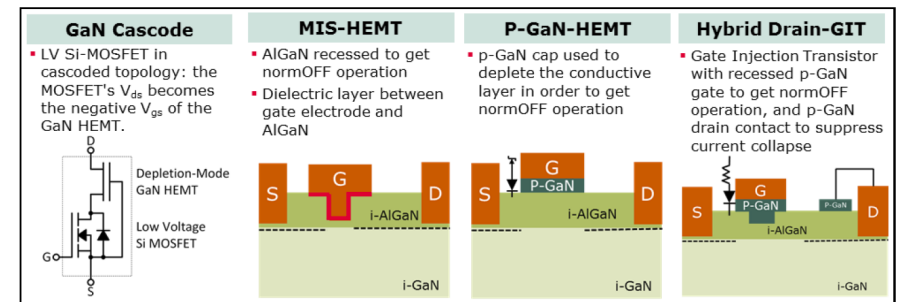
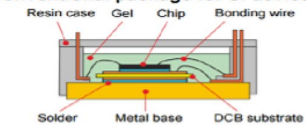


Figure 60. Schematic Representation of Four Example Power GaN Device Structures

### Conventional package for Si device



### New package for SiC device

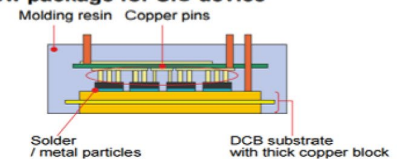


Figure 65. Conventional Power Module Cross Section versus New Power Module for SiC Technology

# Power Supply & Converter Trends

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- AC-DC Front-End Power Supplies
  - AC-DC External Power Supplies
  - Isolated DC-DC Converters
  - Non-Isolated DC-DC Converters
  - Power Supply on a Chip (PSiP)
  - Power Supply on a Chip (PwrSoC)
  - A Subsection of Non-Isolated DC-DC Converters
- *Note: % = number of designs (not production quantity)*



# AC-DC Front-End Power Supplies (200-2,000W)

- Market: “Efficiency!” → “Power Density!”
  - Platinum → Titanium...? Cost?
- HVDC input
  - 2019 = 9% → 2021 = 16%
- Bridgeless Topologies (AC/PFC)
  - 2019 = 11% → 2021 = 24%
- Wide Band Gap
  - Big Increase in SiC, GaN
  - Reduction in Si FETs, IGBTs
- Digital, digital, digital control



# AC-DC External Power Supplies

- Market:
  - USB-A and custom connector → USB-C, USB-PD/PPS
  - Bigger phone batteries (and 5G) → higher power chargers
  - “One-for-all” & more 2-/3-output chargers
- Efficiency up, Power Density up
  - 2x smaller, 2x lighter
- Topology, Frequency
  - CrCM PFC (BLB?), QRF, ACF, LLC, buck...
  - 65 kHz – 600 kHz
  - Bobbin → planar transformer
- Wide Band Gap
  - Si → GaN
  - Aftermarket → In-box



# Isolated DC-DC Converters

- Full brick → half → quarter → custom?
- More 'narrow' 48V<sub>IN</sub> (2019 = 12% → 2023 = 21%)
- More HVDC (26% → 30%)
- 150 kHz → 500 kHz → 1 MHz
- Wide Band Gap (primary switch)
  - Si            2019 = 70%    → 2021 = 26%
  - GaN        2019 = 4%        → 2021 = 54%



# Non-Isolated DC-DC Converters

- Load V down  $\sim 25$  mV / year, but A & W up 10% / year
  - 1.2 V to stay  $\sim 25\%$ , also 1.8 V for Intel (FIVR on-board regulators)
  - Others moving from  $\sim 1$  V to  $\sim 0.6$  V<sub>OUT</sub>
- Focus was power density, EMI, noise  
→ now power density, transient response & heat (efficiency)
- 12 V<sub>IN</sub> → 48 V<sub>IN</sub> (high-end server, automotive)
- Very slow Si → GaN conversion (cost)
- PSiP (Power Supply in Package ( $\leq 1$  in<sup>3</sup>, include L, C)
  - Most  $\sim 12$  V<sub>IN</sub>, 3-10 A<sub>OUT</sub> can be 100 A (1.2 V)
  - Focus power density, easy-to-use
- PwrSoC (Power Supply on Chip)
  - Embedded L, C (e.g. FIVR, iVRM)
  - Early research into GaN integration

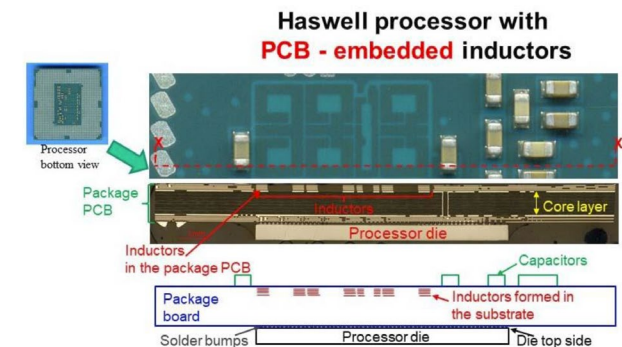


Figure 91. Granular FIVR within the Intel Haswell Processor (source: LTEC Corporation)

“The Research Lab Today Holds The  
Future’s New Products”

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# International University Research



THE OHIO STATE UNIVERSITY

*Special thanks*



THE UNIVERSITY OF TEXAS AT AUSTIN



哈爾濱工業大學  
HARBIN INSTITUTE OF TECHNOLOGY



**ETH** zürich

*25 universities invited to participate, 13 responded*

# Responding University Data

University or Institution	Number of Tenured or Tenure Track Faculty	Number of Instructors or Non-Tenure Track Faculty	Number of Master's Degree Students	Number of Ph.D. Students	Approximate Annual Research Funding (US\$)
Federal University Of Santa Catarina	1	3	12	4	500,000
Harbin Institute Of Technology	14	10	90	40	25,000,000
MIT	3	1	10	20	No Response
NC State/ FREEDM Center	No Response	No Response	No Response	No Response	No Response
Ohio State University	7	1	20	38	5,000,000
Polytechnic University of Madrid	5	2	12	6	1,000,000
Swiss Federal Institute Of Technology	No Response	No Response	No Response	No Response	No Response
Tyndall Research Institute	No Response	No Response	No Response	No Response	No Response
University of Aalborg	30	20	50	75	3,000,000
University of Arkansas - Fayetteville	14	5	20	60	10,000,000
University Of Colorado - Boulder	3	4	50	20	1,500,000
University of Illinois, Urbana-Champaign	3	—	20	20	700,000
University of Texas at Austin	2	5	3	20	1,000,000
Xi'an Jiaotong University	16	2	110	40	1,500,000

# Most Common Research Areas

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- Renewable energy related power electronics
  - Converters for solar, wind and energy storage
  - AC and DC microgrids: systems, converters, controls
- Electrification of transportation
  - Converters for electric vehicle drive systems
  - Battery chargers and battery management systems
  - Power electronics for aerospace & marine applications
- Application of wide bandgap devices (SiC, GaN)
  - Medium voltage converters incl. motor drives and solid-state transformers
- Advanced packaging and integration
  - High power modules
  - Power Supply on Chip (PwrSoC)
  - Power Supply in Package (PSiP)
  - Integration of power devices with drivers and control
- ***Drivers: “Follow the money”***
- ***Most government-funded, focus:***
  - ***Climate change***
  - ***Economic, industrial competitiveness***
  - ***Emphasis on electric transportation and renewable energy***



# Least Common

- Wide band gap *devices*
- MHz+ converters
- Switched capacitor converters
- Robotics
- Server/data center power
- Digital power (0)

# Unique Topics

- Ohio State
  - Converters, motor drives operating at the high end of medium voltage (69 kV)
- ETH Zurich
  - Automating the design process (optimize vs. efficiency, power conversion density, initial cost, and life cycle cost)
- University of Texas – Austin
  - Gallium oxide (GaO) power semis for very HV switching devices

# Industrial Sponsorship Of Research is Small

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- Power supply companies are ahead of academia
- Difference in research goals
  - Academia: publications
  - Industry: ready-to-manufacture product / revenue
- Conflict over IP (including patents)
  - Universities: “we thought it up, we own it”
  - Industry: “we paid for it, we own it”

*The differences can be resolved but each side has to give something*

# Thank you, 谢谢



Capacitor



Education



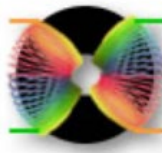
Energy Harvesting



Energy Management



Lead-Free



Magnetics



Packaging & Manufacturing



Power Technology Roadmap



Reliability



Safety & Compliance



Semiconductor



Transportation PowerElectronics

**2019 PSMA POWER TECHNOLOGY ROADMAP**

*Empowering the Electronics Industry*

**Organizing Committee Chairs**

Dhawal B. Dalal ON Semiconductor	Conor Quinn Artesyn Embedded Technologies
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**Segment Leaders**

Ajay Hari ON Semiconductor Application Trends 2015, 2017, 2019	Upal Sengupta Continental Corporation Application Trends 2019
Vittorio Crisafulli ON Semiconductor Component Technologies 2017, 2019	Tim McDonald Infineon Technologies Component Technologies 2017, 2019
Mark Scott Miami University Isolated Dc-Dc Converters 2019	Ian Mazza Vicar Inc. Isolated Dc-Dc Converters 2013, 2015, 2017, 2019
Xin Zhang IBM Non-Isolated Dc-Dc Converters 2019	Jeff Nilles Independent Consultant Non-Isolated Dc-Dc Converters 2015, 2017, 2019
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Robert V. White Embedded Power Labs University Research 2019	Brian Zahnstecher PowerRax Ac-Dc Front-End Power Supplies 2015, 2017, 2019